## Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment
1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>NA</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>NA</td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.
<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Torx screw driver</td>
<td>T15</td>
</tr>
<tr>
<td>Description #2 Cross screw driver</td>
<td>6mm</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unfix system side cover screw*1 then remove side cover.
2. Remove front panel from system.
3. Displug all cable connector from motherboard and all devices.
4. Unfix Front IO cable screw*1 then remove it.
5. Unfix PSU screw*4 then remove it
6. Unfix MB screw*8 then remove it from chassis
7. Remove coin cell battery on MB.
8. Remove WLAN cards
9. Remove Memory
10. Remove H/S screw*4 then remove it from MB

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove side cover
   1. Release thumb screw on the access panel
   2. Griping the tab at the end of access panel, pull towards the rear and remove from unit.
2. Remove main bezel
   1. Release 3 main bezel hooks.
   2. Take out main bezel.
3. Unplug all cable

1. Power cable (24 pin)
2. Heat sink cable
3. 12V power cable (4 pin)
4. Audio cable
5. Front USB and card reader
6. HDD SATA and power cable
7. ODD SATA and power cable
8. WLAN antenna cable
9. Power SW/LED cable
10. SATA cable
11. Cable tie
4. Remove Front I/O
1. Unfix 1 screw from chassis
2. Remove Front I/O

Pull
5. Remove PSU
1. Unfix 4 screw front chassis.
2. Remove PSU from chassis
3. Remove O/P Cable tie.
4. Unscrew from cover.
5. Slide cover to the left.
6. Slide cover to the down.
7. Remove L/N from PCB.
8. Remove Fan wire from PCB.
9. Unscrew & remove PCB from chassis.
10. Remove Electrolytic Capacitor

PSG instructions for this template are available at EL-MF877-01
PSG instructions for this template are available at [EL-MF877-01](#)
PSG instructions for this template are available at EL-MF877-01
PSG instructions for this template are available at EL-MF877-01
6. Remove Mother board

1. Unfix 4 screws from chassis
2. Remove M/B from chassis

Remove coin battery from MB
7. Remove WLAN card
   1. Unfix 1screw and remove WLAN card
   2. Remove WLAN card

Photo 2
8. Remove Memory
   1. Release memory socket
   2. Remove Memory

9. Remove Heat Sink
   1. Unfix 4 screws from Heat Sink
   2. Remove Heat Sink